















Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
---	---	---	---	---	---	-----------

06 121 FR4 35 L20.35 P10

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

06_121_FR4_35_L20.35_p10

Layers	in μ	Material	Build-Up	Assembly		
Layer-1	35 μ	Copper		} B		
	100 μ	Prepreg				
	100 μ	Prepreg				
Layer-2	35 μ	Copper				} A1
	200 μ	L-FR4				
Layer-3	35 μ	Copper				} B
	100 μ	Prepreg				
	100 μ	Prepreg				
Layer-4	35 μ	Copper				
	200 μ	L-FR4				
Layer-5	35 μ	Copper		} B		
	100 μ	Prepreg				
	100 μ	Prepreg				
Layer-99	35 μ	Copper				

© Copyright by Printed Circuit Boards GmbH